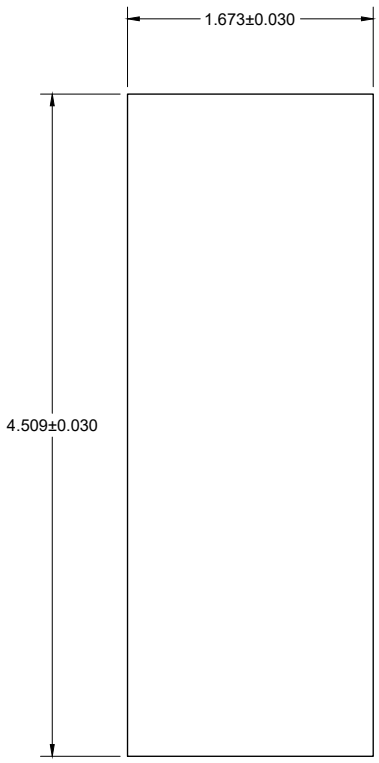
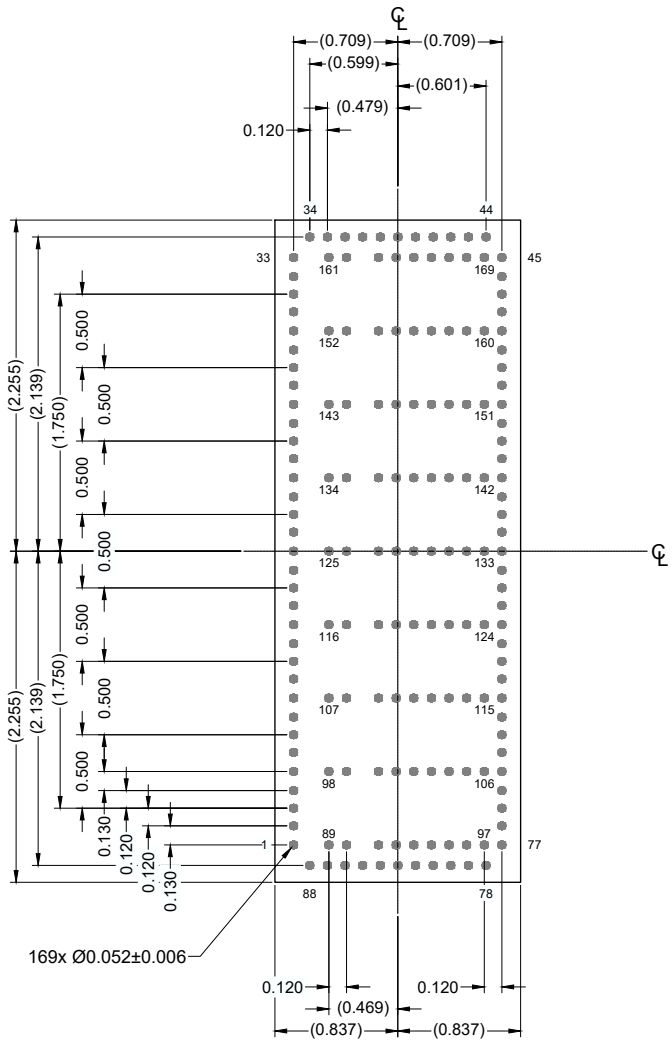
Bumped Die Outline Drawing

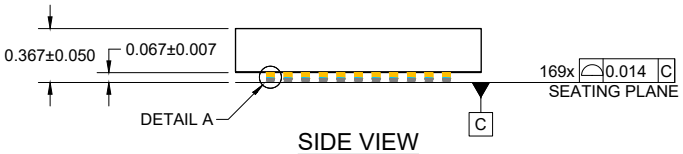
Package Code: DICE
DICEW 1.673 x 4.509 x 0.367 mm Body, 0.120mm Pitch
PSC-4927-01, Revision: 00, Date Created: Dec 21, 2021



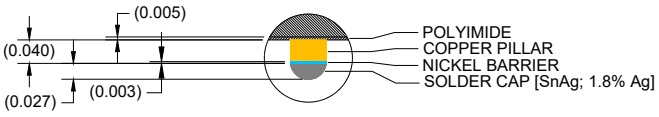
TOP VIEW



BOTTOM VIEW



SIDE VIEW



DETAIL A

NOTES:
1. All dimensions are in millimeters (mm) and angles are in degrees
2. Tolerances of ±0.007mm apply to untoleranced dimensions
3. Dimensions in parenthesis ( ) are for reference only

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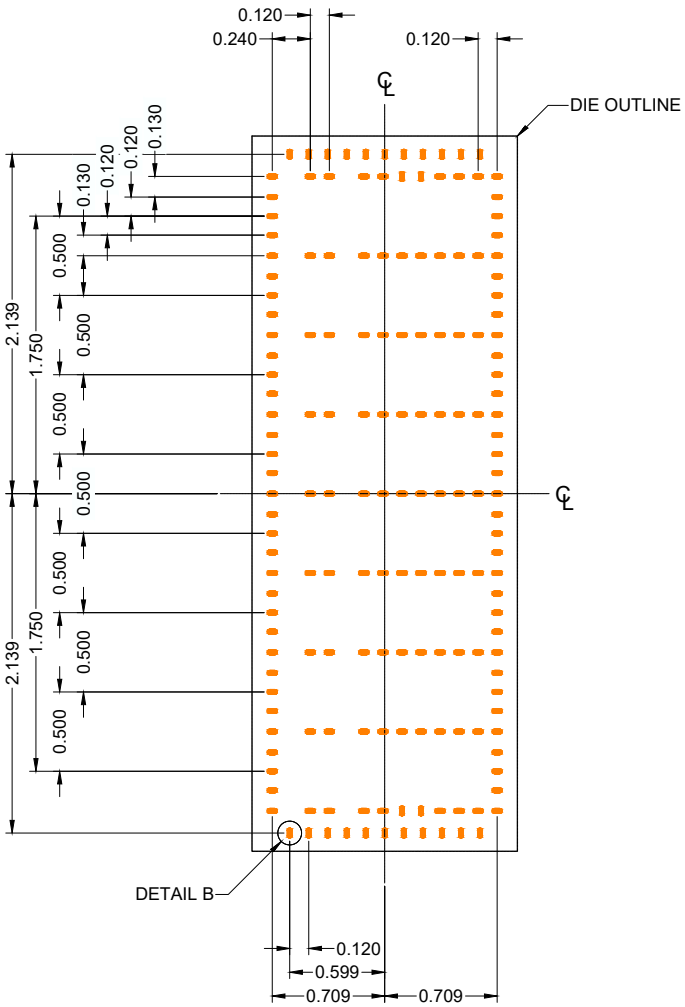
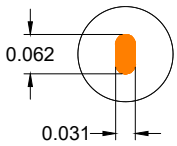


RECOMMENDED LAND PATTERN
(Substrate Top View, NSMD Design)



DETAIL B

SIDE VIEW CROSS-SECTION OF
BUMP ON TRACE FROM DETAIL B

NOTES:
1. All dimensions are in millimeters (mm) and angles are in degrees.
2. Land Pattern exhibits substrate pads for die bump connections.
3. A complete layout requires additional connections and ground patterns.

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